Compliant with IEC 62474/ D9.00

MICROCHIP  Semiconductor Device Type: AEZC (RPX) 036 VQFN 6x6x0.9 Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				JEDEC 97 Product Marking and/or Pkg. Labeling e3
		"Contained In"	% Fotal Weight			26.10	(mg) Total	Mold Compound	% ot Total Weight	17.33
Basic Substance	CAS Number	Sub-Component	•	mg/part	ppm		,			-
Silica, vitreous (or fused)	60676-86-0	Mold Compound	14.731	22.184	147,305		Silica, vitreous (or fused)		85.00	
Epoxy Resin	Trade Secret	Mold Compound	1.508	2.271	15,077		Epoxy Resin	Trade Secret	8.70	
Phenolic Resin Carbon Black	Trade Secret 1333-86-4	Mold Compound  Mold Compound	1.040 0.052	1.566 0.078	10,398 520		Phenolic Resin Carbon Black	Trade Secret 1333-86-4	6.00 0.30	
Copper	7440-50-8	Lead Frame	72.322	108.917	723,219		Carbon Black	Total	100.00	
Iron	7439-89-6	Lead Frame	1.779	2.679	17,790	114.00	(mg) Total	Lead Frame	% of Total Weight	75.70
Silver	7440-22-4	Lead Frame	1.442	2.079	14,421	114.00	Copper	7440-50-8	95.54	75.70
Zinc	7440-22-4	Lead Frame	0.095	0.143	946			7440-50-8 7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.095	0.143	625		Iron Silver	7439-89-6	1.91	
Silver	7440-22-4	Die Attach	0.062	0.094	1,425		Zinc	7440-22-4	0.13	
Epoxy resin	Trade Secret	Die Attach	0.048	0.213	475		Phosphorous	7723-14-0	0.13	
Silicon	7440-21-3	Chip (Die)	4.210	6.340	42,100		1 Hospitorous	Total	100.00	
Copper	7440-57-5	Wire Bond	0.764	1.151	7,644	0.29	(mg) Total	Die Attach	% of Total Weight	0.19
Palladium	7440-05-3	Wire Bond	0.016	0.023	156	0.23	Silver	7440-22-4	75.00	0.13
Tin	7440-03-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.790	2.696	17.900		Epoxy resin	Trade Secret	25.00	
****	7 1 10 01 0	TOTALS:		150.600	1,000,000		Epoxy resiri	Total	100.00	
	0.4500	g Total Mass	100.000	100.000	1,000,000	6.34	(mg) Total	Chip (Die)	% of Total Weight	4.21
		•	,		EU (31 March		Doped Silicon	7440-21-3 <b>Total</b>	100.00 100.00	
ompliance with the above EU Directives has been verified via interna	al design controls	s, supplier declarations, and /or analytical test data.	to the best o		,		Doped Silicon			
impliance with the above EU Directives has been verified via interna in chemical substance is absent from the list above, the chemical su corporated's knowledge and belief as of the date of this document,	al design controls bstance is NOT a there is no credib	s, supplier declarations, and /or analytical test data. n intentional ingredient in the semiconductor device and, le reason to believe that the unavoidable impurity concen		of Microchip To	echnology	1.17	Doped Silicon  (mg) Total			0.78
ompliance with the above EU Directives has been verified via internal a chemical substance is absent from the list above, the chemical su corporated's knowledge and belief as of the date of this document, not below the threshold of regulatory concern for any regulatory solding compounds used by Microchip meet the UL94 V0 flammabilit	al design controls bstance is NOT a there is no credib cheme world-wide	s, supplier declarations, and /or analytical test data.  n intentional ingredient in the semiconductor device and, le reason to believe that the unavoidable impurity concent.	tration of the	of Microchip To e chemical sub	echnology	1.17		Total	100.00	0.78
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on 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) with compliance with the above EU Directives has been verified via internation and chemical substance is absent from the list above, the chemical substance is absent from the list above, the chemical substance is absent from the list above, the chemical substance is absent from the list above, the chemical substance is not below the threshold of regulatory concern for any regulatory so tolding compounds used by Microchip meet the UL94 V0 flammability://ul.com/global/eng/pages/offerings/industries/chemicals/plastics he protective "tubes" in which the specific product is shipped are mertain "reels" may be made from PVC plastic.  Ilicrochip Technology Incorporated believes the information in this foreir original packing materials is true and correct to the best of its knompleteness and accuracy of data in this form because it has been conformation is often protected from disclosure as trade secrets and strovided only as estimates of the average weight of these parts and to f dopants, metals, and non-metal materials contained within silicon	al design controls bstance is NOT a there is no credib cheme world-wide ty standard for play ade from polyvin; orm concerning si towledge and beli compiled based to ome information in the average weigh	s, supplier declarations, and /or analytical test data.  n intentional ingredient in the semiconductor device and, le reason to believe that the unavoidable impurity concent.  astics. You can access the UL iQTM family of databases to yl chloride (PVC) plastic. "Window envelopes" used to houbstances restricted by RoHS in Microchip Technology In ef, as of the date listed in this form. Microchip Technology in the ranges provided in Material Safety Data Sheets provary not have been provided by subcontract assemblers at to fanticipated significant toxic metals components. These	tration of the obtain a test obtain a test of the packin corporated's y Incorporate ided by raw and raw mater	of Microchip To e chemical sul at report at ag slip on the of a semiconduct ad cannot gua material supplirial suppliers.	echnology ostance, if any, outer box and or devices in rantee the iers. Supplier Information is	1.17	(mg) Total	Total Wire Bond 7440-50-8	100.00 % of Total Weight 98.00	0.78
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